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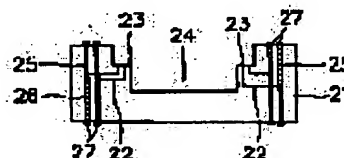
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**(54) SEMICONDUCTOR SUBSTRATE, SEMICONDUCTOR PACKAGE AND MANUFACTURE OF SEMICONDUCTOR PACKAGE AND MULTILAYERED SEMICONDUCTOR PACKAGE MODULE****(57)Abstract:**

**PROBLEM TO BE SOLVED:** To provide a semiconductor substrate capable of high integration, a semiconductor package using the semiconductor substrate and a manufacturing method of the semiconductor package and a multilayered semiconductor package module.

**SOLUTION:** In a semiconductor substrate which has step-difference portions 23 whose upper surfaces are almost horizontally formed on the upper surface and the almost central part of a nonconductive substrate body 21 and in which a cavity 24 accommodating a semiconductor chip is cut and formed, a plurality of viaholes 25 penetrating the upper and the lower surfaces of the substrate main body 21 are bored and formed in the substrate body 21 around the cavity 24, and a plurality of electric wires 22 serving as wirings to the semiconductor chip are so arranged inside the substrate body 21 that the upper surfaces of the stepped portions 23 and the insides of the viaholes 25 are connected. Thus the semiconductor substrate is constituted. The semiconductor chip is stuck in the cavity 24 of the semiconductor substrate, the viaholes 25 are filled with metal bars 26 composed of conductive material, and a semiconductor package is constituted. A multilayered semiconductor package module is constituted by stacking a plurality of the semiconductor packages.

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